

Vishay Siliconix

RoHS

COMPLIANT

HALOGEN

P-Channel 40 V (D-S) MOSFET

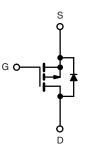
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
- 40	0.077 at V _{GS} = - 10 V	- 4.4	7 nC			
- 40	0.108 at V _{GS} = - 4.5 V	- 3.7	7110			

FEATURES

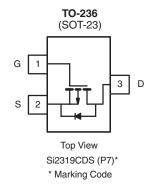
- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Load Switch
- DC/DC Converter



P-Channel MOSFET



Ordering Information: Si2319CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, Parameter Drain-Source Voltage Gate-Source Voltage		Symbol	Limit	Unit	
		V _{DS}	- 40 ± 20		
		V _{GS}			
	T _C = 25 °C		- 4.4		
	T _C = 70 °C		- 3.5		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C	- I _D	- 3.1 ^{b, c}		
	T _A = 70 °C		- 2.5 ^{b, c}	А	
Pulsed Drain Current		I _{DM}	- 20		
	T _C = 25 °C		- 2.1		
Continous Source-Drain Diode Current	T _A = 25 °C	- I _S	- 1 ^{b, c}		
	T _C = 25 °C		2.5		
Marian David Disabation	T _C = 70 °C		1.6		
Maximum Power Dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	W	
	T _A = 70 °C	1	0.8 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 5 s$	R _{thJA}	75	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	50	C/W	

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 166 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	•					
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 40			V
V _{DS} Temperature Coefficient	_{DS} Temperature Coefficient $\Delta V_{DS}/T_J$			- 40		m\//°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l _D = - 250 μΑ		4.8		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 1.2		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Cata Valtaga Drain Current	I _{DSS}	$V_{DS} = -40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current		$V_{DS} = -40$ V, $V_{GS} = 0$ V, $T_{J} = 55$ °C	- 5		- 5	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \leq$ - 5 V, V_{GS} = - 10 V	- 20			А
Drain Course On State Desistance ²	Б	V _{GS} = - 10 V, I _D = - 3.1 A		0.064	0.077	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2.6 A		0.090 0.	0.108	
Forward Transconductance ^a g _{fs}		V _{DS} = - 15 V, I _D = - 3.1 A		10		S
Dynamic ^b						
nput Capacitance C _{iss}			595			
Output Capacitance	C _{oss}	V _{DS} = - 20 V, V _{GS} = 0 V, f = 1 MHz		76		pF
Reverse Transfer Capacitance	C _{rss}	1		61		
Table Oaks Observe	Q _g Q _{gs}	$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -3.1 \text{ A}$		13.6	21	
Total Gate Charge				7	11	
Gate-Source Charge		$V_{DS} = -20 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.1 \text{ A}$		2.5		nC
Gate-Drain Charge	Q _{gd}			3.2		
Gate Resistance	Rg	f = 1 MHz	0.8	4.3	8.6	Ω
Turn-On Delay Time	t _{d(on)}			40	60	
Rise Time	t _r	V_{DD} = - 20 V, R _L = 8 Ω		27	41	1
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 2.5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		18	27	
Fall Time	t _f]		10	20	
Turn-On Delay Time	t _{d(on)}			8	16	ns
Rise Time	se Time t _r			9	18]
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ - 2.5 A, V_GEN = - 10 V, R_g = 1 Ω		20	30	-
Fall Time	t _f			8	16	
Drain-Source Body Diode Characteristic	cs	·		•	•	
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			- 2.1	Δ
Pulse Diode Forward Current	I _{SM}				- 20	A
Body Diode Voltage	V _{SD}	I _S = - 2.5 A, V _{GS} = 0 V		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			17	26	ns
Body Diode Reverse Recovery Charge	Q _{rr}			9	18	nC
Reverse Recovery Fall Time	t _a	I _F = - 2.5 A, dl/dt = 100 A/μs, T _J = 25 °C		10		- ns
Reverse Recovery Rise Time	t _b	1 1		7		

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

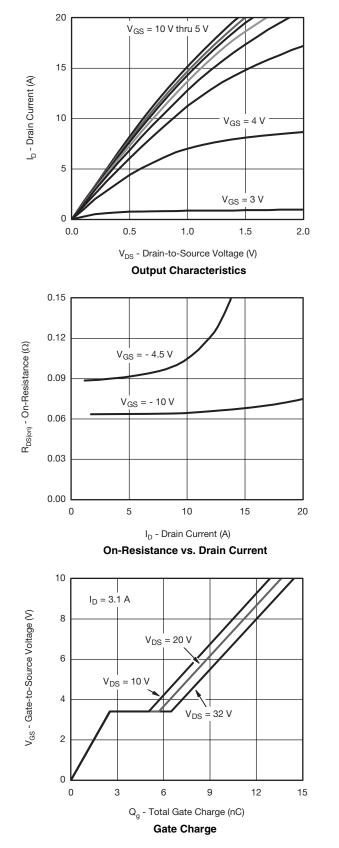
b. Guaranteed by design, not subject to production testing.

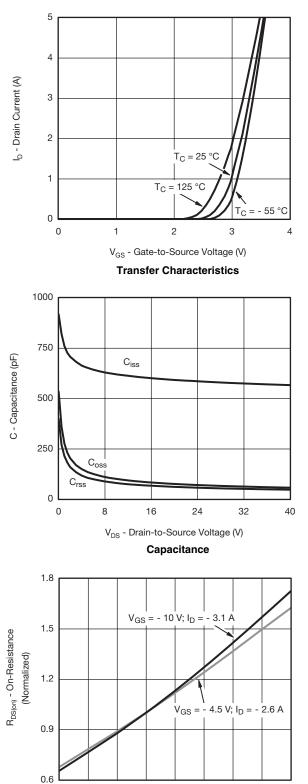
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





T_J - Junction Temperature (°C) On-Resistance vs. Junction Temperature

50

75

100

125

150

- 25

0

25

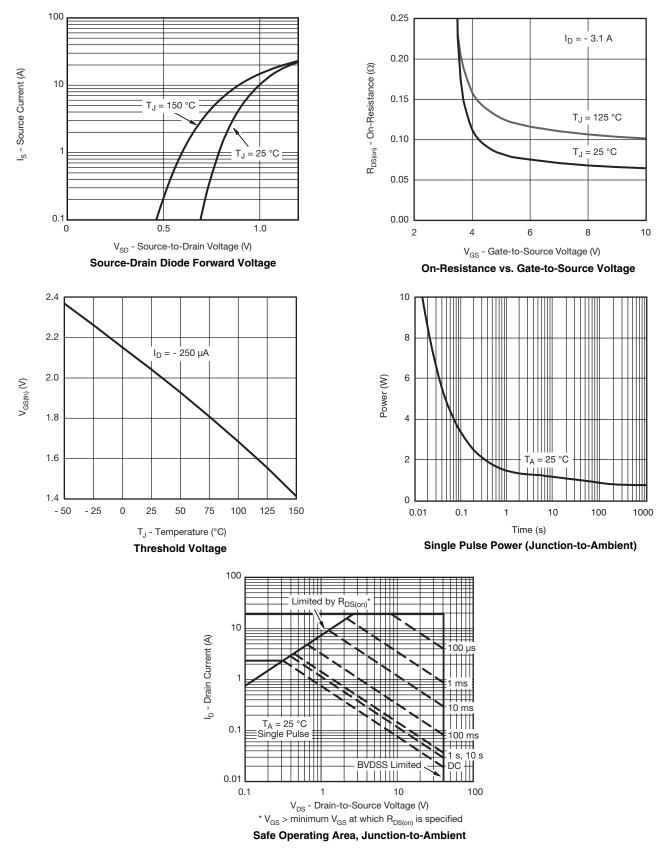
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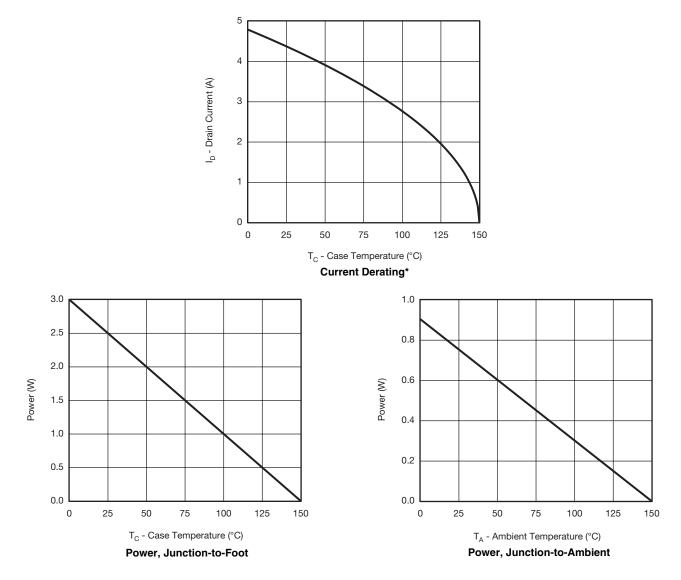


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



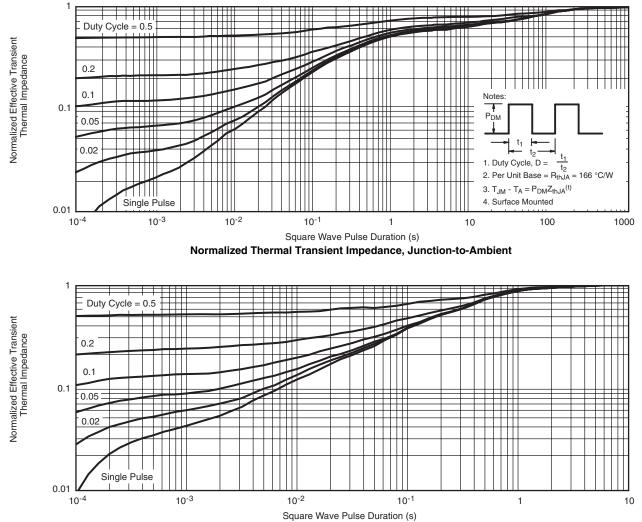
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?66709.



Package Information

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SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	METERS	INCHES		
	Min	Max	Min	Мах	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	



Application Note 826

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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